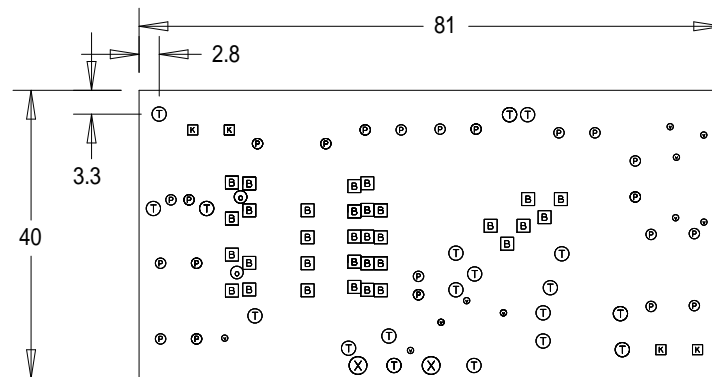


SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)		
BOARD THICKNESS		1.6mm /63mils	
STACKUP	DFTM /2LAYERS		
MINIMAL GAP		150um /6.0mils	
MINIMAL SLIVER		150um /6.0mils	
COPPER THICKNESS		35um(1oz)at START	
FINISH THICKNESS	CHEMICAL NiAu		
SOLDER MASK		GREEN TOP&BOT	
SILKSCREEN	WHITE TOP&BOT		
ALL BOARD ELECTRICALLY TESTED			
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK			


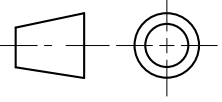
For outline details use gerber



DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILLIMETERS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	0.5 VIA	+0.0/-0.0	PLATED	10
⊙	0.8	+0.1/-0.05	PLATED	22
⊕	1.0	+0.1/-0.05	PLATED	19
⊗	1.1	+0.1/-0.05	PLATED	2
⊠	1.2	+0.1/-0.05	PLATED	32
⊡	1.4	+0.1/-0.05	PLATED	4
⊙	1.6	+0.1/-0.05	PLATED	2

		W25/2019
indice	Description	Date
Controle par :		Autorise par:
<div> ON semiconductor</div>		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE 
Board:	NCP1362-HV EVb -B-TLS	Subc. DYPE TECH
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